

Title (en)

A method and arrangement for fluidizing and/or thermal curing of and/or drying a coating

Title (de)

Verfahren und Vorrichtung zum Verteilen und/oder zur thermischen Aushärtung und/oder zum Trocknen einer Beschichtung

Title (fr)

Dipositif et procédé pour étaler et/ou durcir thermiquement et/ou sécher un revêtement

Publication

**EP 1078693 A1 20010228 (EN)**

Application

**EP 99116621 A 19990825**

Priority

EP 99116621 A 19990825

Abstract (en)

A arrangement comprising a device 1 for heating an anti-corrosive coating in a cavity (22) of a vehicle body (2), suitable for directing a medium, being of a temperature required for thermal curing of the coating or drying or fluidizing the coating (22, 23), in the cavity (21). Preferably, guidance elements (3) help to precisely direct the medium (A, B, C) into the cavity (21). <IMAGE>

IPC 1-7

**B05C 9/14**; **B05C 11/06**; **B05C 7/00**

IPC 8 full level

**B05C 7/00** (2006.01); **B05C 9/14** (2006.01); **B05C 11/06** (2006.01)

CPC (source: EP)

**B05C 7/00** (2013.01); **B05C 9/14** (2013.01); **B05C 11/06** (2013.01); **B05B 13/0627** (2013.01)

Citation (applicant)

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- [A] DE 4027634 A1 19920305 - TITTEMEYER ENGINEERING GMBH [DE]
- [A] US 4101623 A 19780718 - WEBSTER JOHN DAVID, et al
- [X] PATENT ABSTRACTS OF JAPAN vol. 1995, no. 09 31 October 1995 (1995-10-31)
- [X] PATENT ABSTRACTS OF JAPAN vol. 016, no. 261 (C - 0950) 12 June 1992 (1992-06-12)
- [A] PATENT ABSTRACTS OF JAPAN vol. 009, no. 233 (C - 304) 19 September 1985 (1985-09-19)

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EP1477231B2

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)

**EP 1078693 A1 20010228**; AT E270926 T1 20040715; AU 6693400 A 20010319; CZ 2002605 A3 20030115; DE 60012190 D1 20040819; DE 60012190 T2 20050804; EP 1206323 A1 20020522; EP 1206323 B1 20040714; ES 2223565 T3 20050301; PT 1206323 E 20041029; WO 0114071 A1 20010301

DOCDB simple family (application)

**EP 99116621 A 19990825**; AT 00954499 T 20000714; AU 6693400 A 20000714; CZ 2002605 A 20000714; DE 60012190 T 20000714; EP 0006719 W 20000714; EP 00954499 A 20000714; ES 00954499 T 20000714; PT 00954499 T 20000714